CoaXPress 2.0 Quad/Octo Connection Device FMC

EASII

FMC-CXP-12G Device Microchip

FPGA Mezzanine Card

PRODUCT BRIEF

The EASii-IC CoaXPress Device FMC Board is a 4-connection, stackable to 8-connection, single-width board, compatible with the ANSI/VITA 57.1 FPGA Mezzanine Card (FMC) standard. Each board provides 4 device connections compliant with the CoaXPress 2.0 and 1.1.1 standards operating at up to 12.5 Gbps. Two boards can be stacked to provide up to 8 connections.

ABOUT COAXPRESS

CoaXPress standard defines a cost effective and easy interfacing between video devices and acquisition hardware over RG59 and RG6 coaxial cables. It enables hot-plug of devices and 24V power-over-cable with up to 13 Watts per cable.

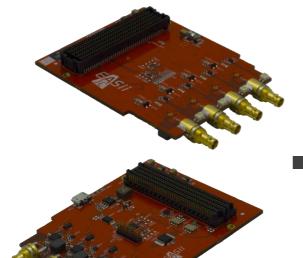
A device can support multiple cameras of many video stream formats. Video streams are sent to a host at a selectable high-speed downlink connection rate from 1.25 Gbps to 12.5 Gbps per cable, with up to 8 cables per device to increase the total bandwidth to 100 Gbps.

Device and cameras can be controlled from a host through the uplink connection at 41.66 Mbps. The standard also provides a low latency, accurate trigger interface between device and host.

CoaXPress supports GenlCam international standard, providing a generic programming interface for all kinds of cameras regardless of the interface technology.

EASII-IC CXP 2.0 DEVICE FMC USAGE

Prototyping



EASii-IC CXP 2.0 DEVICE FMC FEATURES

- JIAA CXP-001-2019 CoaXPress 2.0 compliant & JIAA CXP-001-2015 CoaXPress 1.1.1 compliant
- ANSI / VITA 57.1 FPGA Mezzanine Card compliant
- 4 coaxial 75 ohms HD-BNC connectors

 Providing 4 Coax Press device connections at operations

Providing 4 CoaXPress device connections at operating bitrates from 1.25 Gbps to 12.5 Gbps

- 1 Samtec FMC HPC connector for connections with the carrier board
- FPGA targets: Xilinx, Intel, Micosemi Xilinx 7-series/Zynq, Ultrascale, Ultrascale+/MPSoC; Intel V-series, 10-series; Microsemi Polarfire
- Stackable to provide up to 8 devices connections through a 2nd Samtec FMC HPC connector

PRODUCT DETAILS

Dimensions: 84.00 mm x 69.00 mm Number of lavers: 8 lavers Board thickness: 1.6 mm MICROCHIP EQCO125X40 Coaxial cable driver: Coaxial connectors: HD-BNC Amphenol 034-1018-12G FMC main connector: Samtec ASP-134488-01 Samtec ASP-134486-01 FMC extender connector: red/green bicolor Power, Connections, PoCXP Input power source: 12V from carrier or 5-12V from USB connector

EASII-IC CXP 2.0 DEVICE FMC DELIVERABLES

- FMC Board
- Reference Designs based on EASii-IC CXP 2.0 Device IP
- User Manual

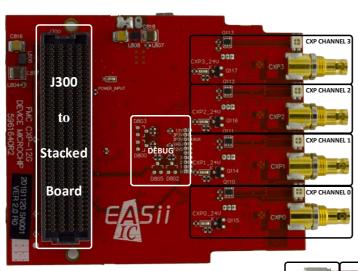


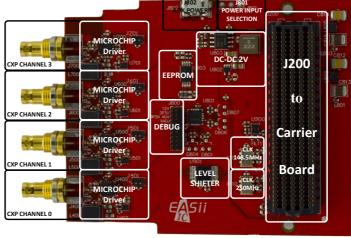


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EASII-IC CXP DEVICE FMC BOARD





CONTACT US

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